

## Preface of the 2011 IAENG International Conference on Electrical Engineering Special Session: Design, Analysis and Tools for Integrated Circuits and Systems

The International Workshop DATICS-IMECS'11: Design, Analysis and Tools for Integrated Circuits and Systems in the International MultiConference of Engineers and Computer Scientists 2011 (IMECS 2011) will take place in Hong Kong, 16-18 March, 2011.

DATICS Workshops were initially created by a network of researchers and engineers both from academia and industry in the areas of Design, Analysis and Tools for Integrated Circuits and Systems. Recently, DATICS has been extended to the fields of Communication, Computer Science, Software Engineering and Information Technology.

The main target of DATICS-IMECS'11 is to bring together software/hardware engineering researchers, computer scientists, practitioners and people from industry to exchange theories, ideas, techniques and experiences related to all aspects of DATICS.

The International Program Committee (IPC) of DATICS-IMECS'11 consists of about 100 experts in the related fields of DATICS-IMECS'11 both from academia and industry. DATICS-IMECS'11 is partnered with CEOL: Centre for Efficiency-Oriented Languages (Ireland), International Software and Productivity Engineering Institute (USA), Intelligent Support Ltd., (United Kingdom), Miteos (Italy), Electronic Center (Italy), Legale Fiscale (Italy), LS Industrial Systems (South Korea), Solari (Hong Kong), Ejitec (China) and Xi'an Jiaotong-Liverpool University - XJTLU (China - UK).

DATICS-IMECS'11 received 15 full-paper submissions from 9 different countries around the world. These submissions were sent to the members of the IPC and additional reviewers for review. Every submission received at least two independent reviews. We would like to thank the IPC members and the reviewers for their hard work and dedication. The DATICS-IMECS'11 Technical Program includes a keynote lecture and 6 papers (acceptance rate of 40%) which are organized into lecture sessions.

On behalf of the IPC, we would like to welcome the delegates and their guests to the DATICS-IMECS'11. We hope that you will enjoy the workshop and find the DATICS-IMECS'11 Technical Program exciting.

Ka Lok Man, Michele Mercaldi and Jieming Ma, DATICS-IMECS'11 IPC Chairs.

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